

SPEC SHEET (FOR REFERENCE)	SHEET No.	G05096A	Page.
			1 of 1

TYPE : 6PC2202N1T**

CHIP SIZE	0.4 * 0.4 mm
WAFER SIZE	6 inch
POSSIBLE DIE PER WAFER	95,200 pcs

Maximum Ratings(Ta=25°C)

Characteristics	Symbol	Ratings	Unit
Drain-source voltage	VDSS	20	V
Gate-source voltage	VGSS	±8	V
Drain Current (DC)	ID	0.7	A

* For Reference

WAFER PROBING SPEC (Ta=25°C)

No	MODE	LIMIT				CONDITIONS
		MIN.	Typ	MAX.	UNIT	
1	IGSS1			±2	uA	VGS=±8V VDS=0V
2	IGSS2			±0.5	uA	VGS=±4.5V VDS=0V
3	IDSS			0.5	uA	VDS=20V VGS=0V
4	BVDSS	22			V	ID=100uA
5	VTH	0.53		0.95	V	ID=250uA
6	RDS(on)1		0.25	0.6	Ω	VGS=4.5V ID=540mA
7	RDS(on)2		0.35	0.75	Ω	VGS=2.5V ID=500mA
8	RDS(on)3		0.5	1.2	Ω	VGS=1.8V ID=350mA
9	VSD	0.5		1.1	V	I=115mA VGS=0V
10	Yfs	400			mS	VDS=10V Id=200mA

※ Built-in ZD between Gate and Source.

NOTE: